

**Electronic Supplementary Information for:**

**Atomic Layer Deposition of B<sub>2</sub>O<sub>3</sub>/SiO<sub>2</sub> Thin Films and Their  
Application in an Efficient Diffusion Doping Process**

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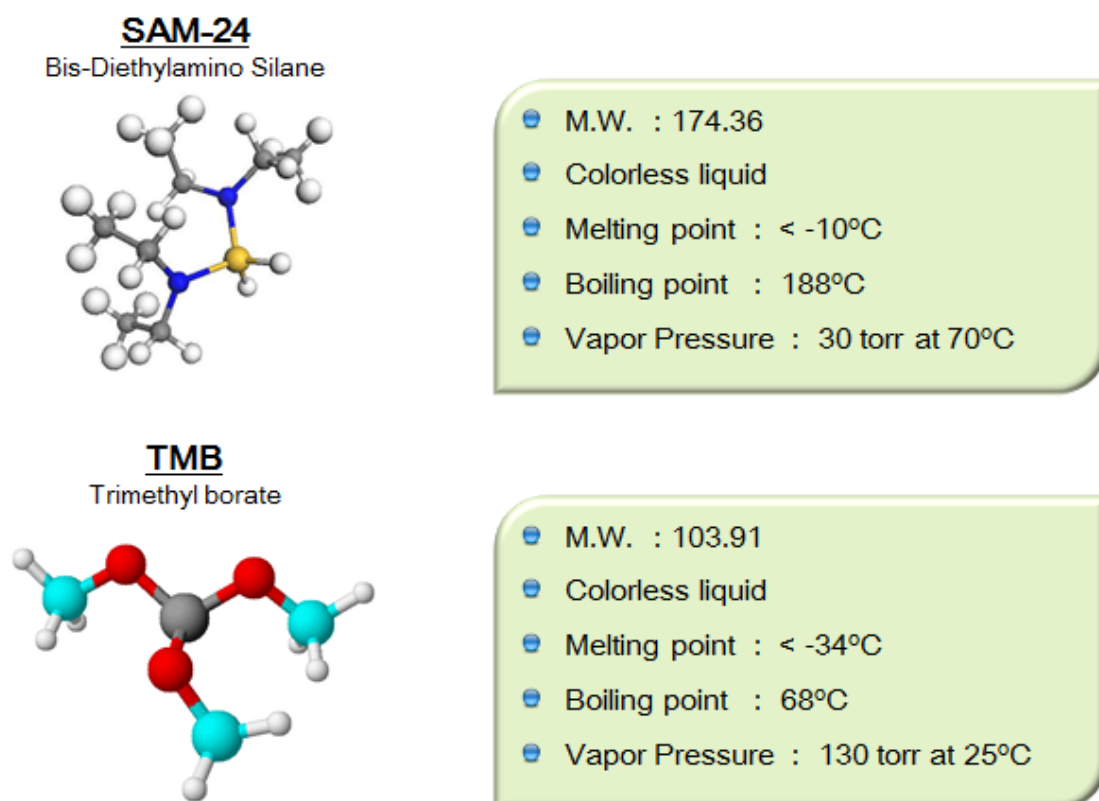
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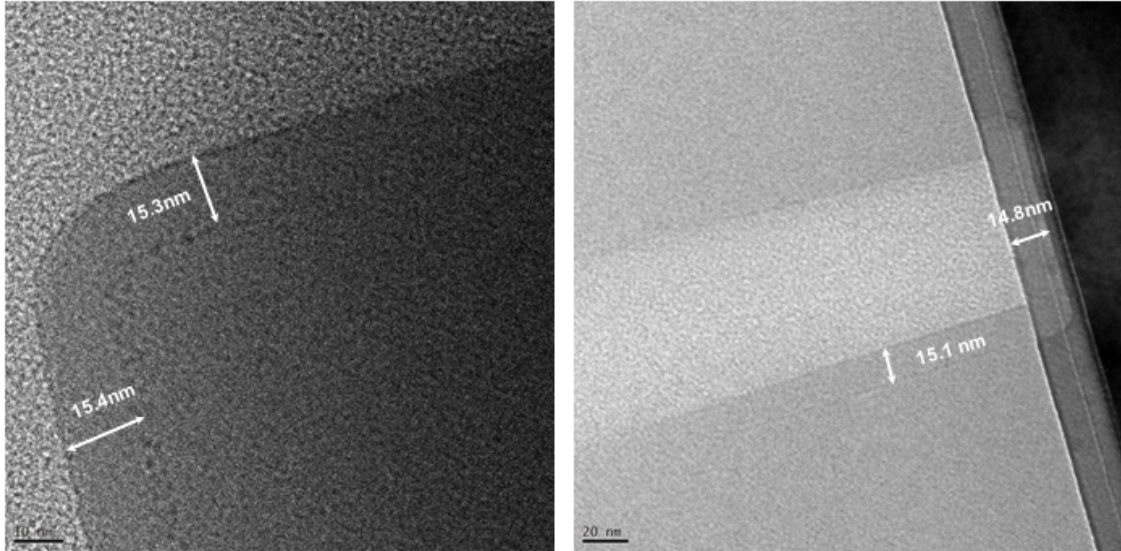
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## (1) Precursor information used in this study



**Figure S1.** Detailed precursor information for ALD of SiO<sub>2</sub> (upper part) and B<sub>2</sub>O<sub>3</sub> (lower part).

## (2) Conformality of ALD SiO<sub>2</sub> film in a via hole structure

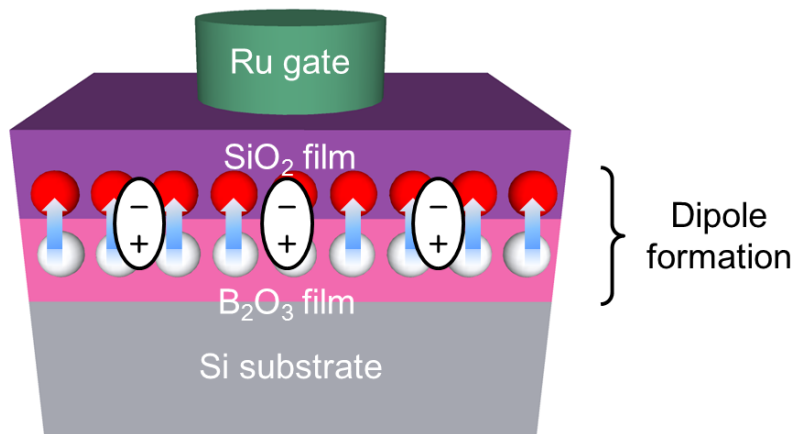


**Figure S2.** Cross-sectional transmission electron microscopy (X-TEM) images for 15 nm-thick ALD SiO<sub>2</sub> film deposited by using SAM-24 and O<sub>2</sub> plasma in a nanoscale via hole (aspect ratio of 5:1).

### (3) Formation of interface dipole layers by oxygen areal density model<sup>1)</sup>

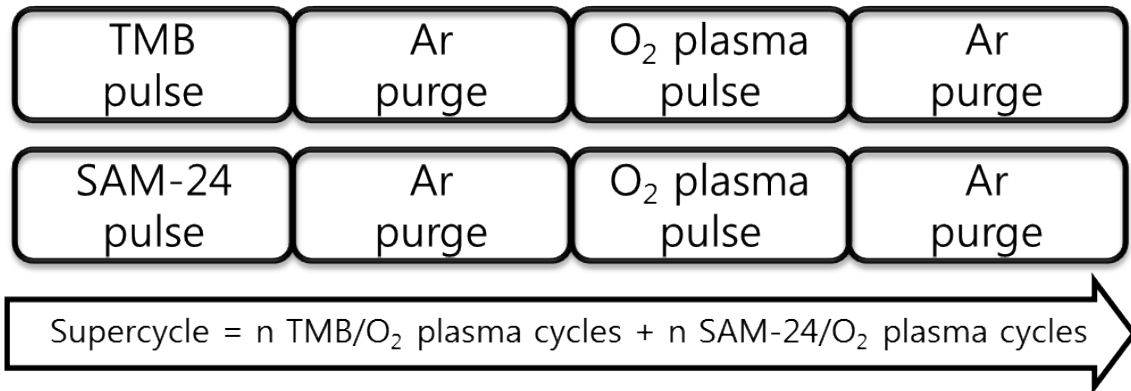
**Table S1.** Summary of structural parameters of SiO<sub>2</sub> and B<sub>2</sub>O<sub>3</sub>, including density, volume of unit structure containing one oxygen atom ( $V_u$ ), and normalized areal oxygen density ( $\sigma/\sigma_{SiO_2}$ ).

Oxides	SiO <sub>2</sub>	B <sub>2</sub> O <sub>3</sub>
Density (g/cm <sup>3</sup> )	2.2	2.55(Trigonal)/3.11(Monoclinic)
Unit structure	Si <sub>1/2</sub> O	B <sub>2/3</sub> O
$V_u$ (Å <sup>3</sup> )	22.7	15.1(Trigonal)/12.4(Monoclinic)
$\sigma/\sigma_{SiO_2}$	1.00	1.31(Trigonal)/1.49(Monoclinic)



**Figure S3.** Schematic of the formation of interface dipole layers due to the oxygen transfer, in the form of negatively charged ion, creating the positively charged oxygen vacancies in higher  $\sigma$  oxide region, and negatively charged center in lower  $\sigma$  oxide region.

**(4) Preparation of B-doped SiO<sub>2</sub> films with different B/(B+Si) composition**



**Figure S4.** Schematic of the atomic layer deposition (ALD) supercycle, composed of n repetitions of alternating B<sub>2</sub>O<sub>3</sub> and SiO<sub>2</sub> growth cycles.

## Reference

- (1) Kita, K.; Toriumi, A., Origin of electric dipoles formed at high-k/SiO<sub>2</sub> interface.

*Appl. Phys. Lett.* **2009**, *94*, 132902-132902-3.